

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

1-16 (cancelled)

17. (currently amended) A surface treatment process, comprising: providing a hydrophillic surface; polishing said surface with a slurry that comprises a suspension of abrasive particles in deionized water and TMAH, whereby said surface is rendered hydrophobic; and thereby causing all of said abrasive particles to be removed when said surface is rinsed in deionized water, said abrasive particles having a mean diameter of between about 1 and 10,000 microns, wherein the TMAH has a concentration in said deionized water of between about 2% and 20%.

18. (cancelled)

19. (original) The process described in claim 17 wherein said abrasive particles are selected from the group consisting of alumina and silica.

20. (cancelled)

21. (original) The process described in claim 17 wherein said hydrophilic surface is selected from the group consisting of tungsten, silicon oxide, and copper.

22. (currently amended) A surface treatment process, comprising: providing a hydrophillic surface; polishing said surface with a slurry that comprises a suspension of abrasive particles in deionized water and TBAH, whereby said surface is rendered hydrophobic; and thereby causing all of said abrasive particles to be removed when said surface is rinsed in deionized water, said abrasive particles having a mean diameter of between about 1 and 10,000 microns, wherein the TBAH has a concentration in said deionized water of between about 2 and 20%.

23. (cancelled)

24. (original) The process described in claim 22 wherein said abrasive particles are selected from the group consisting of alumina and silica.

25. (cancelled)

26. (original) The process described in claim 22 wherein said hydrophilic surface is selected from the group consisting of tungsten, silicon oxide, and copper.

27-30 (cancelled)